

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Panasonic

XN0F261

Silicon NPN epitaxial planar type

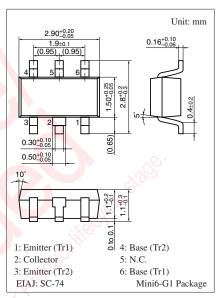
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■ Features

- Two elements incorporated into one package (Collector-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

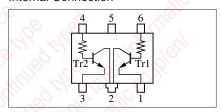
■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit | |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V _{CBO} | 30 | V | |
| Collector-emitter voltage (Base open) | V _{CEO} | 20 | V | |
| Emitter-base voltage (Collector open) | V_{EBO} | 5 | V | |
| Collector current | I_C | 600 | mA | |
| Total power dissipation | P_{T} | 300 | mW | |
| Junction temperature | T_{j} | 150 | °C | |
| Storage temperature | T _{stg} | -55 to +150 | °C | |



Marking Symbol: 6B

Internal Connection



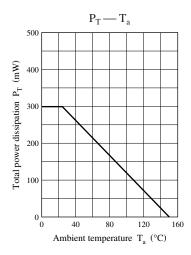
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

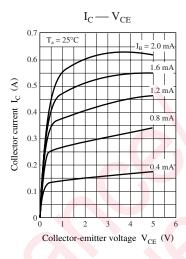
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|----------------------------------------------|----------------------|----------------------------------------------------------------------|------|-----|------|------|
| Collector-base voltage (Emitter open) | V_{CBO} | $I_C = 1 \mu A, I_E = 0$ | 30 | | | V |
| Collector-emitter voltage (Base open) | V _{CEO} | $I_C = 1 \text{ mA}, I_B = 0$ | 20 | | | V |
| Emitter-base voltage (Collector open) | V _{EBO} | $I_E = 1 \mu A, I_C = 0$ | 5 | | | V |
| Collector-base cutoff current (Emitter open) | I_{CBO} | $V_{CB} = 30 \text{ V}, I_{E} = 0$ | | | 1 | μΑ |
| Emitter-base cutoff current (Collector open) | I _{EBO} | $V_{EB} = 5 \text{ V}, I_{C} = 0$ | | | 1 | μΑ |
| Forward current transfer ratio | h _{FE} | $V_{CE} = 5 \text{ V}, I_{C} = 50 \text{ mA}$ | 100 | | 600 | _ |
| Collector-emitter saturation voltage | V _{CE(sat)} | $I_C = 50 \text{ mA}, I_B = 2.5 \text{ mA}$ | | | 80 | mV |
| Input resistance | R ₁ | 6/2 | -30% | 3.3 | +30% | kΩ |
| Transition frequency | f_T | $V_{CB} = 10 \text{ V}, I_{E} = -50 \text{ mA}, f = 200 \text{ MHz}$ | | 200 | | MHz |

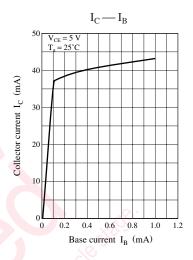
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

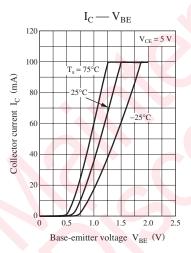
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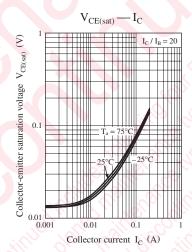
Panasonic

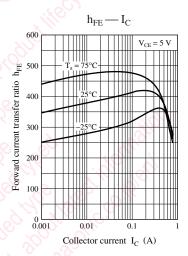












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